



#### 30V P-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8

# **Product Summary**

BVDSS	Rds(on) Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C
-30V	$15m\Omega$ @ V <sub>GS</sub> = -10V	-42A
	25mΩ @ V <sub>GS</sub> = -5V	-32A

# **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

#### **Features and Benefits**

- Low R<sub>DS(ON)</sub> ensures on-state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMP3021SFVWQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

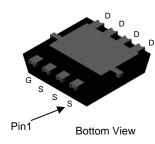
# **Mechanical Data**

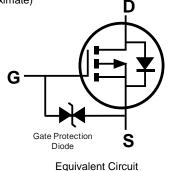
- Case: PowerDI<sup>®</sup>3333-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
   Weight: 0.072 grams (Approximate)





Top View





#### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMP3021SFVWQ-7	PowerDI3333-8 (SWP) (Type UX)	2,000/Tape & Reel
DMP3021SFVWQ-13	PowerDI3333-8 (SWP) (Type UX)	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

### **Marking Information**



SW2 = Product Type Marking Code

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 21 = 2021)

WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			VDSS	-30	V
Gate-Source Voltage			$V_{GSS}$	±25	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lo	-11 -9	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = -10V	Steady State	$T_C = +25^{\circ}C$ $T_C = +70^{\circ}C$	lo	-42 -34	А
Maximum Continuous Body Diode Forward Currer	Is	-42	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 19	Ірм	-128	Α		
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)			I <sub>SM</sub>	-128	Α
Avalanche Current (Note 8) L = 1mH			las	-13	А
Avalanche Energy (Note 8) L = 1mH			Eas	84	mJ

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	PD	1	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	RθJA	126.6	°C/W
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	P <sub>D</sub>	2.5	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	RθJA	51.2	°C/W
Thermal Resistance, Junction to Case (Note 7)	R <sub>0</sub> JC	3.6	°C/W	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

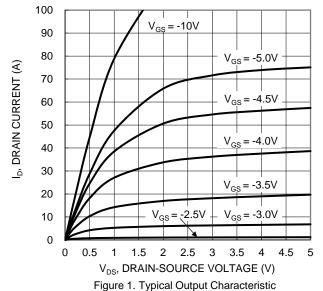
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	_		V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	-1	μA	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	lgss	_	_	±10	μA	$V_{GS} = \pm 25V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	Vgs(TH)	-1.0	_	-2.5	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$	
Static Drain-Source On-Resistance	Process	_	10.3	15	mΩ	$V_{GS} = -10V, I_D = -8A$	
Static Dialii-Source Off-Resistance	RDS(ON)		15.5	25	11122	$V_{GS} = -5V, I_{D} = -5A$	
Diode Forward Voltage	VsD	_	-0.7	-1.2	V	Vgs = 0V, Is = -1A	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	_	1799	_	pF	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	259	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	225	_	pF		
Gate Resistance	Rg	_	2.1	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = -5V)	Qg	_	17.4	_	nC	V <sub>DS</sub> = -15V, I <sub>D</sub> = -10A	
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	_	34	_	nC		
Gate-Source Charge	Qgs	_	5.1	_	nC		
Gate-Drain Charge	Qgd		8.4	_	nC		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	6.5	_	ns		
Turn-On Rise Time	tR	_	18.3	_	ns	$V_{DD} = -15V, V_{GS} = -10V,$ $R_{G} = 3\Omega, I_{D} = -10A$	
Turn-Off Delay Time	t <sub>D</sub> (OFF)	_	35.8	_	ns		
Turn-Off Fall Time	tr	_	23.7	_	ns		
Reverse Recovery Time	trr	_	14.9	_	ns	I- 00 dl/dt 5000///-	
Reverse Recovery Charge	Qrr	_	15	_	nC	Is = -8A, dI/dt = 500A/µs	

5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided. Notes:

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
  7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J$  = +25°C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.





25 R<sub>DS(ON)</sub>, DRAIN-SOURCE ON-RESISTANCE 20  $V_{GS} = -5V$ 15 10  $V_{GS} = -10V$ 5 0 10 20 0 15 25 30 I<sub>D</sub>, DRAIN-SOURCE CURRENT (A)

Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

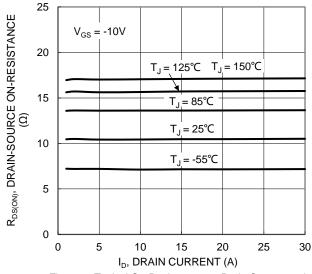


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

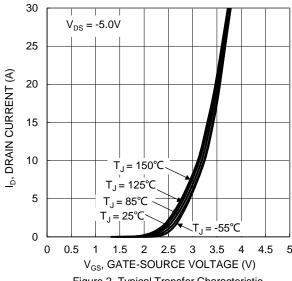


Figure 2. Typical Transfer Characteristic

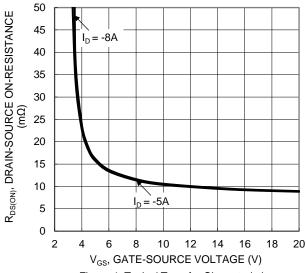


Figure 4. Typical Transfer Characteristic

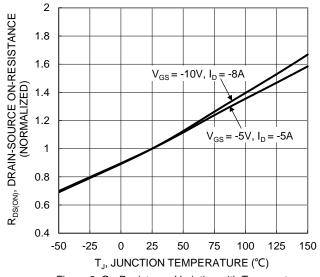


Figure 6. On-Resistance Variation with Temperature



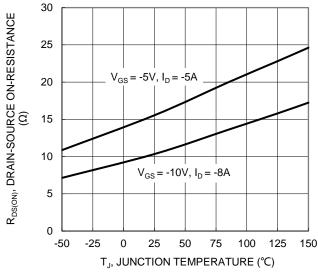
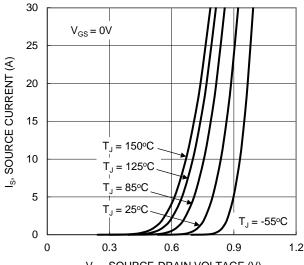
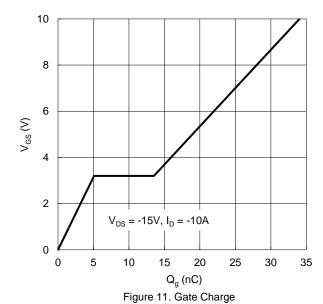


Figure 7. On-Resistance Variation with Temperature

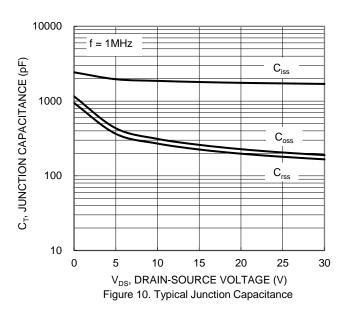


V<sub>SD</sub>, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current



3  $V_{GS(TH)}, \ GATE \ THRESHOLD \ VOLTAGE \ (V)$ 2.5 2  $I_D = -1mA$ 1.5  $I_{D} = -250 \mu A$ 1 0.5 0 -50 -25 0 25 50 75 100 125 150 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Temperature



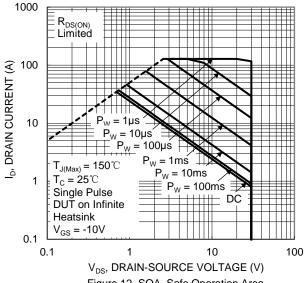


Figure 12. SOA, Safe Operation Area



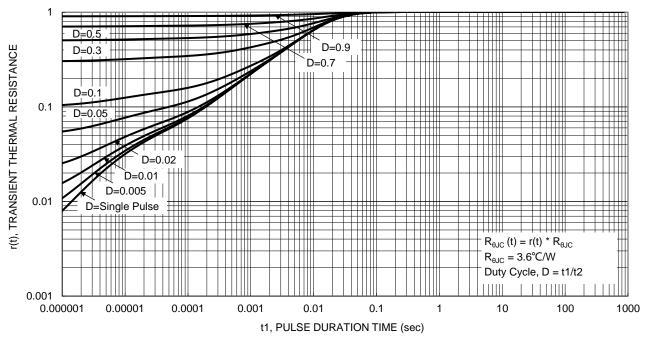


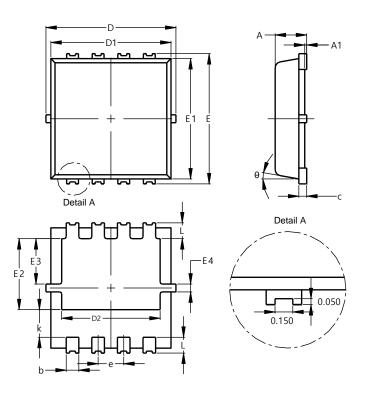
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)

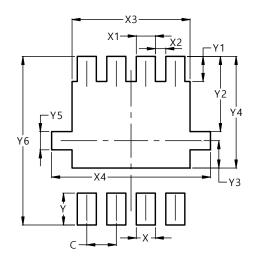


PowerDI3333-8 (SWP)					
(Type UX)					
Dim	Min Max Ty				
Α	0.75	0.85	0.80		
A1	0.00	0.05			
b	0.25	0.40	0.32		
С	0.10	0.25	0.15		
D	3.20	3.40	3.30		
D1	2.95	3.15	3.05		
D2	2.30	2.70	2.50		
E	3.20	3.40	3.30		
E1	2.95	3.15	3.05		
E2	1.60	2.00	1.80		
E3	0.95	1.35	1.15		
E4	0.10	0.30	0.20		
е	_	_	0.65		
k	0.50	0.90	0.70		
L	0.30	0.50	0.40		
θ	0°	12°	10°		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)		
С	0.650		
Х	0.420		
X1	0.420		
X2	0.230		
Х3	2.600		
X4	3.500		
Υ	0.700		
Y1	0.550		
Y2	1.650		
Y3	0.600		
Y4	2.450		
Y5	0.400		
Y6	3.700		



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